

REMARKS

This application has been carefully reviewed in light of the Office Action dated June 29, 2005. New Claims 26 to 33 are in the application, of which Claim 26 is independent. Claims 17 to 19, 21, 24, and 25 have been cancelled without prejudice. Reconsideration and further examination are respectfully requested.

Claims 17 to 19, 21, and 25 were rejected under 35 U.S.C. § 102(b) over Japan 60-146225 (Oota). The rejection is respectfully traversed.

Claim 21 recites, *inter alia*, a substrate having a wiring, wherein the wiring comprises a plurality of recesses arranged in a direction crossing the longitudinal direction of the wiring, and wherein the thickness of the wiring is 30 nm or more at the bottom of each of the plurality of recesses.

Oota is not seen to teach or suggest at least the foregoing features.

The dependent claims are also submitted to be patentable because they set forth additional aspects of the present invention and are dependent from the independent claim discussed above. Therefore, separate and individual consideration of each dependent claim is respectfully requested.

Applicants' undersigned attorney may be reached in our Costa Mesa,
California office by telephone at (714) 540-8700. All correspondence should be directed to
our address given below.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Damond E. Vadnais", written over a horizontal line.

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